



Session Title:	[WD1] New Materials Etching
Session Date:	November 22 (Wed.), 2023
Session Time:	08:30-10:10
Session Room:	Room D (Grand Ballroom 3, 2F)
Session Chair:	Prof. Heeyeop Chae (Sungkyunkwan Univ., Korea)

[WD1-1] 08:30-08:50

Highly Selective Etching of SiGe over Si for GAAFET Fabrication

Seunghyo Lee, Wonje Lee, Kiwon Song, and Sangwoo Lim (Yonsei Univ., Korea)

[WD1-2] 08:50-09:10

Development of Copper Dry Etching Equipment via ECR Plasma Source

Jin Nyoung Jang, Jong Hwa Lee (APS Research Corp., Korea), Sangheon Lee, Kiro Jung (APS Corp., Korea), Donghoon Kim, Mun-Pyo Hong (Korea Univ., Korea), Sang-Gab Kim (Samsung Display Co., Ltd., Korea), Soo Ouk Jang (KFE, Korea), and Chiwoo Kim (APS Corp., Korea)

[WD1-3] [Invited] 09:10-09:40

Implementation of a Plasma-Based Integrated System for Synthesis, Etching, Machine-Learning of 2D TMDc

Hyeong-U Kim (KIMM, Korea)

[WD1-4] [Invited] 09:40-10:10

Extendable Etch Solutions for Sub 10-nm DRAM Device

Kukhan Yoon, Hyejin Choi, Jongkyu Kim, Chanmin Lee, Youngsik Seo, Keumjoo Lee, and Jongmyeong Lee (Samsung Electronics Co., Ltd., Korea)